



## Director Development (Package Technology)

### Job description

As Director - Development, you will be leading and managing a professional team of Package definition/concept engineers, Technology Integration (Complete chain of Assembly process interaction) engineers, Material engineers and Lead frame designers in our Backend Development team.

In your new role you will:

- **Leading and managing** a professional team of **Package definition / concept engineers, Technology Integration** (Complete chain of Assembly process interaction) **engineers, Material engineers and Lead frame designers**.
- Ensuring sufficient resource capacity is available to support the project pipeline.
- Developing & equipping the team members with right skills and competencies to be relevant and empower them to achieve high performance in new package design / concept, technology integration.
- Review, analyse and approve subordinates/ reports.
- Driving and promoting technical leadership towards greater technical competency in all subjects matter expertise (i.e. **concept engineering, technology integration, material engineering & leadframe design**) relevant to package development.
- Be part of the Development management team and is responsible to achieve defined targets i.e. **design-to-cost, design-for-manufacturing, design-for-quality and meeting time to market**.
- Actively **manage problem solving, focus team** and task force in the running projects and ensure delivery of targets.
- **Supporting Development Head** in defining department strategy to achieve business success and technology leadership.
- Interfacing to DIV (ATV, PSS, IPC) located in multi-development locations (i.e. Munich, Villach, Regensburg) and internal partners on package concept, technology integration, material.

### Profile

You are best equipped for this task if you have:

- Min 10 years of relevant experiences in **chip packaging design technology and development, preferably in High Voltage Reinforced Isolated Gate Driver products/packages**
- Education qualification in PhD/Masters /Bachelor's Degree in Engineering (Electrical / Electronics / Microelectronics / Mechanical / Materials etc).

### At a glance

Location: **(Singapore)**  
Job ID: **354342**  
Start date: **Sep 01, 2022**  
Entry level: **5+ years**  
Type: **Full time**  
Contract: **Permanent**

Apply to this position online by following the URL and entering the Job ID in our job search:

Job ID: **354342**  
[www.infineon.com/jobs](https://www.infineon.com/jobs)



- Good **problem solving and analytical skills**
- Good leadership with team management experience
- Good knowledge in **concept engineering, technology integration, material engineering & leadframe design**

## Why Us

**Part of your life. Part of tomorrow.**

Infineon is a world leader in semiconductor solutions that make life easier, safer, and greener. Our solutions for efficient energy management, smart mobility, and secure, seamless communications link the real and the digital world.

*In accordance with the requirements set by the Singaporean Government, Infineon Technologies Asia Pacific Pte Ltd ("Infineon") can only allow individuals who are (a) fully vaccinated, (b) certified to be medically ineligible for a vaccine or (c) have recovered from COVID-19 within a prescribed period, onto company premises. Therefore, Infineon requires all new employees, as well as contractors and business partners, to be fully vaccinated against COVID-19. "Fully vaccinated" means individuals have completed the full regime of an approved COVID-19 Vaccine as listed under the World Health Organization (WHO) Emergency Use Listing (EUL) including the respective post-vaccination period to ensure the vaccine has become full effective. Anyone who is unable to be vaccinated due to an approved and/or recognised exemption condition may apply for special consideration.*

